



TJA1046

Dual high-speed CAN transceiver with Standby mode

Rev. 3 — 6 September 2017

Product data sheet

1. General description

The TJA1046 is a dual high-speed CAN transceiver that provides two interfaces between a Controller Area Network (CAN) protocol controller and the physical two-wire CAN-bus. It is composed of two fully independent TJA1044GT transceivers. The transceivers are designed for high-speed CAN applications in the automotive industry, providing the differential transmit and receive capability to (a microcontroller with) a CAN protocol controller. The TJA1046 guarantees robust communication at data rates up to 5 Mbit/s as used in, for example, CAN FD networks

The TJA1046 offers a feature set optimized for 12 V automotive applications and excellent ElectroMagnetic Compatibility (EMC) performance.

Additionally, the TJA1046 features:

- Ideal passive behavior to the CAN-bus when the supply voltage is off
- A very low-current Standby mode with bus wake-up capability
- Excellent EMC performance at speeds up to 500 kbit/s, even without a common mode choke

The HVSON package allows for more than 70 % PCB space saving compared with traditional SO packages. These features make the TJA1046 an excellent choice for networks containing more than one HS-CAN interface requiring a low-power mode with wake-up capability via the CAN-bus, especially for body and gateway control units.

The TJA1046 implements the CAN physical layer as defined in ISO 11898-2:2016 and SAE J2284-1 to SAE J2284-5. Additional timing parameters defining loop delay symmetry are specified. This implementation enables reliable communication in the CAN FD fast phase at data rates up to 5 Mbit/s.

2. Features and benefits

2.1 General

- Two fully independent TJA1044GT HS-CAN transceivers combined in a single package
- Fully ISO 11898-2:2016 and SAE J2284-1 to SAE J2284-5 compliant
- Timing guaranteed for data rates up to 5 Mbit/s
- Improved TXD to RXD propagation delay of 210 ns
- Very low-current Standby mode with host and bus wake-up capability
- Optimized for use in 12 V automotive systems
- EMC performance satisfies 'Hardware Requirements for LIN, CAN and FlexRay Interfaces in Automotive Applications', Version 1.3, May 2012.



- Leadless HVSON14 package (3.0 mm × 4.5 mm) with improved Automated Optical Inspection (AOI) capability
- Can interface with 3.3 V and 5 V-supplied microcontrollers, provided the microcontroller I/Os are 5 V tolerant.
- AEC-Q100 qualified
- Dark green product (halogen free and Restriction of Hazardous Substances (RoHS) compliant)

2.2 Predictable and fail-safe behavior

- Functional behavior predictable under all supply conditions
- Transceivers disengage from bus when not powered (zero load)
- Transmit Data (TXD) and bus dominant time-out functions
- Internal biasing of TXDx and STBx input pins

2.3 Protection

- High ESD handling capability on the bus pins (8 kV IEC and HBM)
- Bus pins protected against transients in automotive environments
- Undervoltage detection on V_{CCx} pins
- Thermally protected

3. Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|--|--|------|-----|------|--------------|
| V_{CC} | supply voltage | on pins V_{CC1} and V_{CC2} | 4.75 | - | 5.25 | V |
| $V_{uvd(stb)}$ | standby undervoltage detection voltage | on pins V_{CC1} and V_{CC2} | 3.5 | 4 | 4.3 | V |
| I_{CC} | supply current | per transceiver: | | | | |
| | | Standby mode | - | 10 | 15 | μ A |
| | | Normal mode; bus recessive | 2 | 5 | 10 | mA |
| | Normal mode; bus dominant | 20 | 45 | 70 | mA | |
| V_{ESD} | electrostatic discharge voltage | IEC 61000-4-2 on pins CANH1, CANH2, CANL1 and CANL2 | -8 | - | +8 | kV |
| V_{CANH} | voltage on pin CANH | pins CANH1 and CANH2; limiting value according to IEC60134 | -42 | - | +42 | V |
| V_{CANL} | voltage on pin CANL | pins CANL1 and CANL2; limiting value according to IEC60134 | -42 | - | +42 | V |
| T_{vj} | virtual junction temperature | | -40 | - | +150 | $^{\circ}$ C |

4. Ordering information

Table 2. Ordering information

| Type number | Package | | Version |
|-------------|---------|---|-----------|
| | Name | Description | |
| TJA1046TK | HVSON14 | plastic, thermal enhanced very thin small outline package; no leads; 14 terminals; body 3 × 4.5 × 0.85 mm | SOT1086-2 |

5. Block diagram

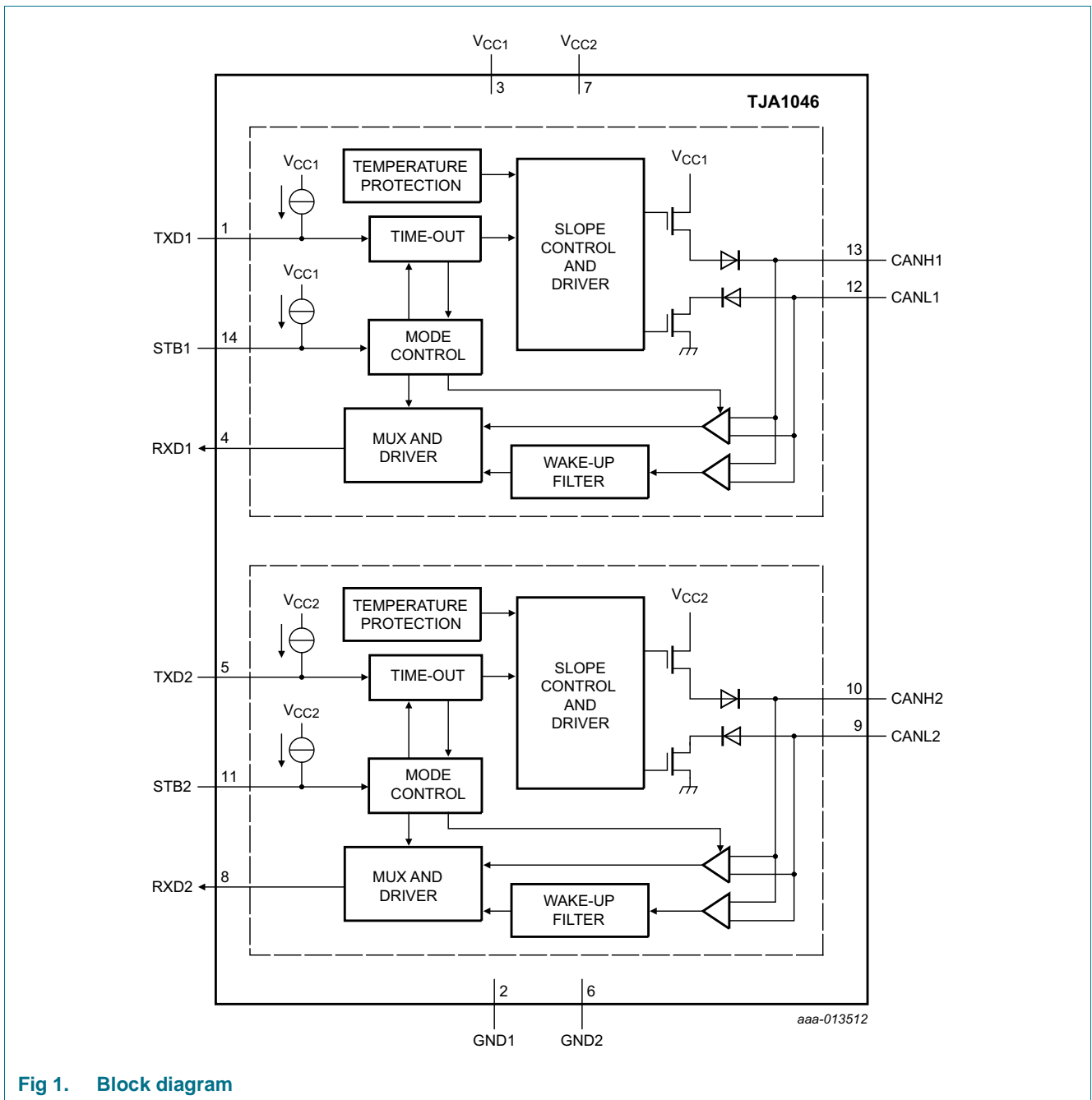
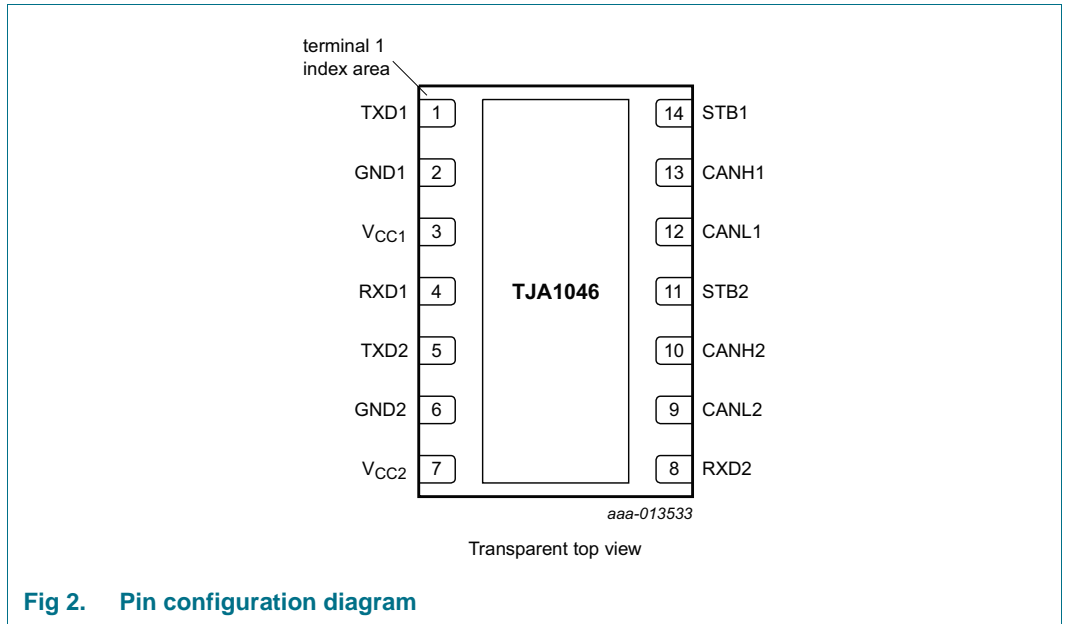


Fig 1. Block diagram

6. Pinning information

6.1 Pinning



6.2 Pin description

Table 3. Pin description

| Symbol | Pin | Description |
|---------------------|-----|--|
| TXD1 | 1 | transmit data input 1 |
| GND1 ^[1] | 2 | transceiver ground 1 |
| V _{CC1} | 3 | transceiver supply voltage 1 |
| RXD1 | 4 | receive data output 1; reads out data from the bus lines 1 |
| TXD2 | 5 | transmit data input 2 |
| GND2 ^[1] | 6 | transceiver ground 2 |
| V _{CC2} | 7 | transceiver supply voltage 2 |
| RXD2 | 8 | receive data output 2; reads out data from the bus lines 2 |
| CANL2 | 9 | LOW-level CAN-bus line 2 |
| CANH2 | 10 | HIGH-level CAN-bus line 2 |
| STB2 | 11 | Standby mode control input 2 |
| CANL1 | 12 | LOW-level CAN-bus line 1 |
| CANH1 | 13 | HIGH-level CAN-bus line 1 |
| STB1 | 14 | Standby mode control input 1 |

[1] HVSON14 package die supply ground is connected to both the GNDx pins and the exposed center pad. The GNDx pins must be connected together externally in the application and soldered to board ground. For enhanced thermal and electrical performance, it is recommended that the exposed center pad also be soldered to board ground.

7. Functional description

7.1 Operating modes

The TJA1046 supports two operating modes per transceiver, Normal and Standby. The operating mode is selected independently for each transceiver via pins STB1 and STB2. See [Table 4](#) for a description of the operating modes under normal supply conditions.

Table 4. Operating modes

| Mode | Inputs | | Outputs | |
|---------|---------------|------------------|------------------|--|
| | Pin STB1/STB2 | Pin TXD1/TXD2 | CAN driver | Pin RXD1/RXD2 |
| Normal | LOW | LOW | dominant | LOW |
| | | HIGH | recessive | LOW when bus dominant HIGH when bus recessive |
| Standby | HIGH | x ^[1] | biased to ground | follows BUS when wake-up detected HIGH when no wake-up detected |

[1] 'x' = don't care

7.1.1 Normal mode

A LOW level on pin STBx selects Normal mode. In this mode, the enabled transceiver can transmit and receive data via the bus lines CANHx and CANLx (see [Figure 1](#) for the block diagram). The differential receiver converts the analog data on the bus lines into digital data which is output on pin RXDx. The slopes of the output signals on the bus lines are controlled internally and are optimized in a way that guarantees the lowest possible EME.

7.1.2 Standby mode

A HIGH level on pin STBx selects Standby mode. In Standby mode, the enabled transceiver cannot transmit or correctly receive data via the bus lines. The transmitter and Normal-mode receiver blocks are switched off to reduce supply current, and only a low-power differential receiver monitors the bus lines for activity.

In Standby mode, the bus lines are biased to ground to minimize the system supply current. The low-power receiver is supplied from V_{CCX} and is able to detect CAN-bus activity. Pin RXDx follows the bus after a wake-up request has been detected. A transition to Normal mode is triggered when STBx is forced LOW.

7.2 Remote wake-up (via the CAN-bus)

The CAN transceivers contain separate wake-up circuits that operate independently of each other. When a dedicated wake-up pattern (specified in ISO 11898-2: 2016) is detected on the bus, the associated transceiver wakes up from Standby mode. This filtering helps avoid spurious wake-up events. A spurious wake-up sequence could be triggered by, for example, a dominant clamped bus or by dominant phases generated by noise or spikes on the bus.

The wake-up pattern consists of:

- a dominant phase of at least $t_{wake(busdom)}$ followed by
- a recessive phase of at least $t_{wake(busrec)}$ followed by

- a dominant phase of at least $t_{wake(busdom)}$

Dominant or recessive bits inserted between these phases that are shorter than $t_{wake(busdom)}$ and $t_{wake(busrec)}$, respectively, are ignored

The complete dominant-recessive-dominant pattern must be received within $t_{to(wake)bus}$ to be recognized as a valid wake-up pattern (see Figure 3). Otherwise, the internal wake-up logic is reset. The complete wake-up pattern will then need to be retransmitted to trigger a wake-up event. Pin RXDx remains HIGH until the wake-up event has been triggered.

After a wake-up sequence has been detected, the transceiver will remain in Standby mode with the bus signals reflected on RXDx. Note that dominant or recessive phases lasting less than $t_{ftr(wake)bus}$ will not be detected by the low-power differential receiver and will not be reflected on RXDx in Standby mode.

A wake-up event is not flagged on RXDx if any of the following events occurs while a valid wake-up pattern is being received:

- The transceiver switches to Normal mode
- The complete wake-up pattern was not received within $t_{to(wake)bus}$
- A V_{CC} undervoltage is detected ($V_{CC} < V_{uvd(stb)}$; see Section 7.3.3)

If any of these events occur while a wake sequence is being received, the internal wake-up logic is reset. The complete wake-up sequence will then need to be retransmitted to trigger a wake-up event.

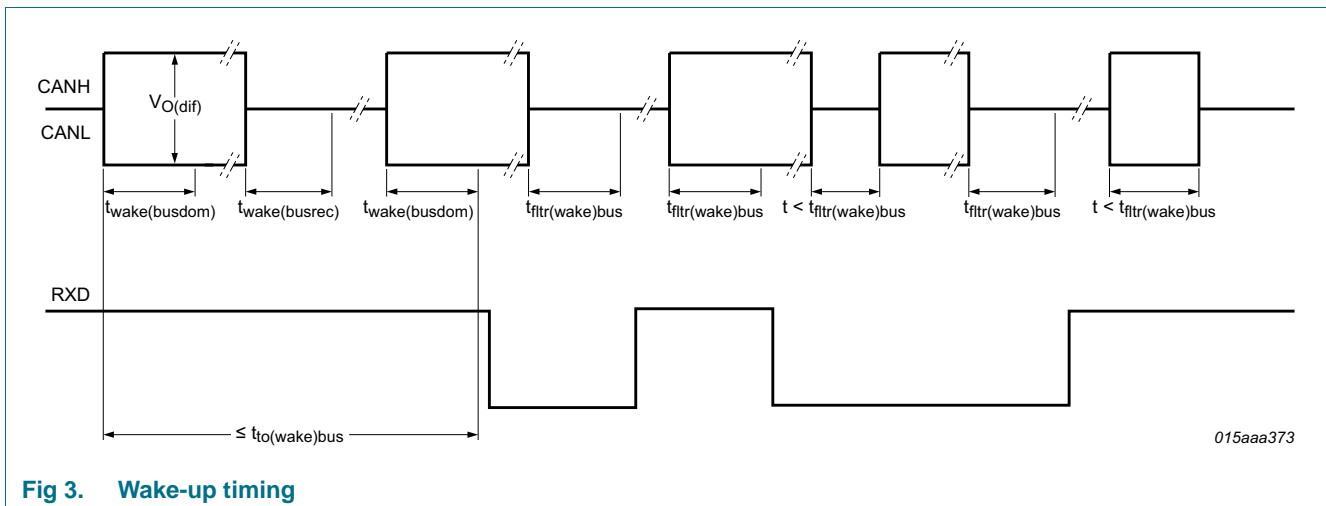


Fig 3. Wake-up timing

7.3 Fail-safe features

7.3.1 TXD dominant time-out function

A 'TXD dominant time-out' timer is started when pin TXDx goes LOW. If the LOW state on this pin persists for longer than $t_{to(dom)TXD}$, the transmitter is disabled, releasing the bus lines to recessive state. This function prevents a hardware and/or software application failure from driving the bus lines to a permanent dominant state (blocking all network communications). The TXD dominant time-out timer is reset when pin TXDx is set HIGH.

The TXD dominant time-out time also defines the minimum possible bit rate of approximately 25 kbit/s. Each of the transceivers in the TJA1046 has its own TXD dominant time-out timer. The two timers operate independently of each other.

7.3.2 Internal biasing of TXDx and STBx input pins

Pins TXDx and STBx have internal pull-ups to V_{CCx} to ensure a safe, defined state in case they are left floating. Pull-up currents flow in these pins in all states; both pins should be held HIGH in Standby mode to minimize supply current.

7.3.3 Undervoltage detection on pins V_{CCx}

The TJA1046 features two fully independent supply voltages. If V_{CCx} drops below the standby undervoltage detection level, $V_{uvd(stb)}$, the transceiver switches to Standby mode. The logic state of pin STBx is ignored until V_{CCx} has recovered. A LOW level on TXDx is also ignored. This precaution prevents the bus being driven dominant while V_{CCx} is recovering. TXDx will continue to be ignored until a HIGH level (bus recessive) is detected.

If V_{CCx} drops below the switch-off undervoltage detection level, $V_{uvd(swoff)}$, the transceiver switches off and disengages from the bus (zero load; bus pins floating) until V_{CCx} has recovered.

Each of the transceivers in the TJA1046 has its own undervoltage protection circuit. The two circuits operate independently of each other.

7.3.4 Overtemperature protection

The output drivers are protected against overtemperature conditions. If the virtual junction temperature exceeds the shutdown junction temperature, $T_{j(sd)}$, both output drivers are disabled. When the virtual junction temperature drops below $T_{j(sd)}$ again, the output drivers recover independently once TXDx has been reset to HIGH. Including the TXDx condition prevents output driver oscillation due to small variations in temperature. Each of the transceivers in the TJA1046 has its own temperature protection circuit. The two circuits operate independently of each other.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). All voltages are referenced to GND.

| Symbol | Parameter | Conditions | Min | Max | Unit |
|--------------------------|---------------------------------------|---|------|-----------------------|------|
| V _x | voltage on pin x ^[1] | on pins CANH1, CANL1, CANH2, CANL2 | -42 | +42 | V |
| | | on pins V _{CC1} , V _{CC2} | -0.3 | +7 | V |
| | | on any other pin ^[2] | -0.3 | V _{CC} + 0.3 | V |
| V _(CANH-CANL) | voltage between pin CANH and pin CANL | | -27 | +27 | V |
| V _{trt} | transient voltage | on pins CANH1, CANL1, CANH2, CANL2 ^[3] | | | |
| | | pulse 1 | -100 | - | V |
| | | pulse 2a | - | 75 | V |
| | | pulse 3a | -150 | - | V |
| | | pulse 3b | - | 100 | V |
| V _{ESD} | electrostatic discharge voltage | IEC 61000-4-2 (150 pF, 330 Ω) ^[4] | | | |
| | | on pins CANH1, CANL1, CANH2, CANL2 | -8 | +8 | kV |
| | | Human Body Model (HBM); 100 pF, 1.5 kΩ ^[5] | | | |
| | | on pins CANH1, CANL1, CANH2, CANL2 | -8 | +8 | kV |
| | | on any other pin | -4 | +4 | kV |
| | | Machine Model (MM); 200 pF, 0.75 μH, 10 Ω ^[6] | | | |
| | | on any pin | -200 | +200 | V |
| | | Charged Device Model (CDM); field Induced charge; 4 pF ^[7] | | | |
| on corner pins | -750 | +750 | V | | |
| on any other pin | -500 | +500 | V | | |
| T _{vj} | virtual junction temperature | ^[8] | -40 | +150 | °C |
| T _{stg} | storage temperature | | -55 | +150 | °C |

- [1] The device can sustain voltages up to the specified values over the product lifetime, provided applied voltages (including transients) never exceed these values.
- [2] Maximum voltage should never exceed 7 V.
- [3] According to IEC TS 62228 (2007), Section 4.2.4; parameters for standard pulses defined in ISO7637 part 2: 2004-06.
- [4] According to IEC TS 62228 (2007), Section 4.3; DIN EN 61000-4-2.
- [5] According to AEC-Q100-002.
- [6] According to AEC-Q100-003.
- [7] According to AEC-Q100-011 Rev-C1. The classification level is C4B.
- [8] In accordance with IEC 60747-1. An alternative definition of virtual junction temperature is: $T_{vj} = T_{amb} + P \times R_{th(vj-a)}$, where $R_{th(vj-a)}$ is a fixed value to be used for the calculation of T_{vj} . The rating for T_{vj} limits the allowable combinations of power dissipation (P) and ambient temperature (T_{amb}).

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Value | Unit |
|---------------|---|------------------|--------|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | dual-layer board | [1] 76 | K/W |
| | | four-layer board | [2] 46 | K/W |

- [1] According to JEDEC JESD51-2, JESD51-3 and JESD51-5 at natural convection on 1s board with thermal via array under the exposed pad connected to the second copper layer.
- [2] According to JEDEC JESD51-2, JESD51-5 and JESD51-7 at natural convection on 2s2p board. Board with two inner copper layers (thickness: 35 μm) and thermal via array under the exposed pad connected to the first inner copper layer.

10. Static characteristics

Table 7. Static characteristics

$T_{vj} = -40\text{ }^{\circ}\text{C}$ to $+150\text{ }^{\circ}\text{C}$; $V_{CC} = 4.75\text{ V}$ to 5.25 V ; $R_L = 60\ \Omega$; $C_L = 100\text{ pF}$ unless specified otherwise; All voltages are defined with respect to ground. Positive currents flow into the IC. [1]

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|-------|------|----------------|---------------|
| Supply; pins V_{CC1} and V_{CC2} | | | | | | |
| V_{CC} | supply voltage | | 4.75 | - | 5.25 | V |
| $V_{uvd(stb)}$ | standby undervoltage detection voltage | | 3.5 | 4 | 4.3 | V |
| $V_{uvd(swoff)}$ | switch-off undervoltage detection voltage | | 1.3 | 2.4 | 3.4 | V |
| I_{CC} | supply current | per transceiver: | | | | |
| | | Standby mode; $V_{TXDx} = V_{CC}$ | - | 10 | 15 | μA |
| | | Normal mode; recessive; $V_{TXDx} = V_{CC}$ | 2 | 5 | 10 | mA |
| | | Normal mode; dominant; $V_{TXDx} = 0\text{ V}$ | 20 | 45 | 70 | mA |
| | | Normal mode; dominant; $V_{TXDx} = 0\text{ V}$; short circuit on bus lines; $-3\text{ V} < (V_{CANH} = V_{CANL}) < +18\text{ V}$ | 2 | 80 | 110 | mA |
| Standby mode control input; pins STB1 and STB2 | | | | | | |
| V_{IH} | HIGH-level input voltage | | 2 | - | $V_{CC} + 0.3$ | V |
| V_{IL} | LOW-level input voltage | | -0.3 | - | 0.8 | V |
| I_{IH} | HIGH-level input current | per transceiver; $V_{STBx} = V_{CC}$ | -1 | - | +1 | μA |
| I_{IL} | LOW-level input current | per transceiver; $V_{STBx} = 0\text{ V}$ | -15 | - | -1 | μA |
| CAN transmit data input; pins TXD1 and TXD2 | | | | | | |
| V_{IH} | HIGH-level input voltage | | 2 | - | $V_{CC} + 0.3$ | V |
| V_{IL} | LOW-level input voltage | | -0.3 | - | 0.8 | V |
| I_{IH} | HIGH-level input current | per transceiver; $V_{TXDx} = V_{CCx}$ | -5 | - | +5 | μA |
| I_{IL} | LOW-level input current | per transceiver; $V_{TXDx} = 0\text{ V}$ | -260 | -150 | -70 | μA |
| C_i | input capacitance | | [2] - | 5 | 10 | pF |
| CAN receive data output; pins RXD1 and RXD2 | | | | | | |
| I_{OH} | HIGH-level output current | per transceiver; $V_{RXDx} = V_{CCx} - 0.4\text{ V}$ | -8 | -3 | -1 | mA |

Table 7. Static characteristics ...continued

$T_{vj} = -40\text{ }^{\circ}\text{C}$ to $+150\text{ }^{\circ}\text{C}$; $V_{CC} = 4.75\text{ V}$ to 5.25 V ; $R_L = 60\text{ }\Omega$; $C_L = 100\text{ pF}$ unless specified otherwise; All voltages are defined with respect to ground. Positive currents flow into the IC.^[1]

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--|--|--|--|--------------|--------------|---------|
| I_{OL} | LOW-level output current | per transceiver; $V_{RDX} = 0.4\text{ V}$; bus dominant | 1 | - | 12 | mA |
| Bus lines; pins CANH1, CANL1, CANH2 and CANL2 | | | | | | |
| $V_{O(dom)}$ | dominant output voltage | $V_{TXDx} = 0\text{ V}$; $t < t_{to(dom)TXD}$ | | | | |
| | | pin CANHx; $R_L = 50\text{ }\Omega$ to $65\text{ }\Omega$ | 2.75 | 3.5 | 4.5 | V |
| | | pin CANLx; $R_L = 50\text{ }\Omega$ to $65\text{ }\Omega$ | 0.5 | 1.5 | 2.25 | V |
| $V_{dom(TX)sym}$ | transmitter dominant voltage symmetry | $V_{dom(TX)sym} = V_{CCx} - V_{CANHx} - V_{CANLx}$ | -400 | - | +400 | mV |
| V_{TXsym} | transmitter voltage symmetry | $V_{TXsym} = V_{CANHx} + V_{CANLx}$; $f_{TXD} = 250\text{ kHz}$, 1 MHz and 2.5 MHz ; $C_{SPLIT} = 4.7\text{ nF}$ | [2] [3] 0.9 V_{CC} | - | 1.1 V_{CC} | V |
| $V_{O(dif)}$ | differential output voltage | dominant; Normal mode; $V_{TXDx} = 0\text{ V}$; $t < t_{to(dom)TXD}$ | | | | |
| | | $R_L = 50\text{ }\Omega$ to $65\text{ }\Omega$ | 1.5 | - | 3 | V |
| | | $R_L = 45\text{ }\Omega$ to $70\text{ }\Omega$ | 1.4 | - | 3.3 | V |
| | | $R_L = 2240\text{ }\Omega$ | 1.5 | - | 5 | V |
| | | recessive; no load | | | | |
| | | Normal mode: $V_{TXDx} = V_{CCx}$ Standby mode | -50 -0.2 | - | +50 +0.2 | mV V |
| $V_{O(rec)}$ | recessive output voltage | Normal mode; $V_{TXDx} = V_{CC}$; no load | 2 | 0.5 V_{CC} | 3 | V |
| | | Standby mode; no load | -0.1 | - | +0.1 | V |
| $V_{th(RX)dif}$ | differential receiver threshold voltage | $-12\text{ V} \leq V_{CANLx} \leq +12\text{ V}$; $-12\text{ V} \leq V_{CANHx} \leq +12\text{ V}$ | | | | |
| | | Normal mode | 0.5 | - | 0.9 | V |
| | | Standby mode | 0.4 | - | 1.15 | V |
| $V_{rec(RX)}$ | receiver recessive voltage | $-12\text{ V} \leq V_{CANL} \leq +12\text{ V}$; $-12\text{ V} \leq V_{CANH} \leq +12\text{ V}$ | | | | |
| | | Normal mode | -4 | - | 0.5 | V |
| | | Standby mode | -4 | - | 0.4 | V |
| $V_{dom(RX)}$ | receiver dominant voltage | $-12\text{ V} \leq V_{CANL} \leq +12\text{ V}$; $-12\text{ V} \leq V_{CANH} \leq +12\text{ V}$ | | | | |
| | | Normal mode | 0.9 | - | 9.0 | V |
| | | Standby mode | 1.15 | - | 9.0 | V |
| $V_{hys(RX)dif}$ | differential receiver hysteresis voltage | $-12\text{ V} \leq V_{CANL} \leq +12\text{ V}$; $-12\text{ V} \leq V_{CANH} \leq +12\text{ V}$; Normal mode | 50 | - | 300 | mV |
| $I_{O(sc)dom}$ | dominant short-circuit output current | per transceiver; $V_{TXDx} = 0\text{ V}$; $t < t_{to(dom)TXD}$; $V_{CC} = 5\text{ V}$ | | | | |
| | | pin CANHx; $V_{CANHx} = -15\text{ V}$ to $+40\text{ V}$ | -100 | -70 | -40 | mA |
| | | pin CANLx; $V_{CANLx} = -15\text{ V}$ to $+40\text{ V}$ | 40 | 70 | 100 | mA |
| $I_{O(sc)rec}$ | recessive short-circuit output current | per transceiver; Normal mode; $V_{CANHx} = V_{CANLx} = -27\text{ V}$ to $+32\text{ V}$; $V_{TXDx} = V_{CC}$; | -5 | - | +5 | mA |

Table 7. Static characteristics ...continued

$T_{vj} = -40\text{ }^{\circ}\text{C}$ to $+150\text{ }^{\circ}\text{C}$; $V_{CC} = 4.75\text{ V}$ to 5.25 V ; $R_L = 60\text{ }\Omega$; $C_L = 100\text{ pF}$ unless specified otherwise; All voltages are defined with respect to ground. Positive currents flow into the IC.^[1]

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------------------|--------------------------------|---|-------------------|-----|-----|--------------------|
| I_L | leakage current | per transceiver; $V_{CC} = 0\text{ V}$ or V_{CC} shorted to GND via $47\text{ k}\Omega$; $V_{CANHx} = V_{CANLx} = 5\text{ V}$ | -5 | - | +5 | μA |
| R_i | input resistance | $-2\text{ V} \leq V_{CANL} \leq +7\text{ V}$; $-2\text{ V} \leq V_{CANH} \leq +7\text{ V}$ | ^[2] 9 | 15 | 28 | $\text{k}\Omega$ |
| ΔR_i | input resistance deviation | $0\text{ V} \leq V_{CANL} \leq +5\text{ V}$; $0\text{ V} \leq V_{CANH} \leq +5\text{ V}$ | ^[2] -3 | - | +3 | % |
| $R_{i(\text{dif})}$ | differential input resistance | $-2\text{ V} \leq V_{CANL} \leq +7\text{ V}$; $-2\text{ V} \leq V_{CANH} \leq +7\text{ V}$ | ^[2] 19 | 30 | 52 | $\text{k}\Omega$ |
| $C_{i(\text{cm})}$ | common-mode input capacitance | | ^[2] - | - | 20 | pF |
| $C_{i(\text{dif})}$ | differential input capacitance | | ^[2] - | - | 10 | pF |
| Temperature detection | | | | | | |
| $T_{j(\text{sd})}$ | shutdown junction temperature | | ^[2] - | 185 | - | $^{\circ}\text{C}$ |

- [1] All parameters are guaranteed over the virtual junction temperature range by design. Factory testing uses correlated test conditions to cover the specified temperature and power supply voltage range.
- [2] Not tested in production; guaranteed by design.
- [3] The test circuit used to measure the bus output voltage symmetry (which includes C_{SPLIT}) is shown in [Figure 8](#).

11. Dynamic characteristics

Table 8. Dynamic characteristics

$T_{vj} = -40\text{ }^{\circ}\text{C}$ to $+150\text{ }^{\circ}\text{C}$; $V_{CC} = 4.75\text{ V}$ to 5.25 V ; $R_L = 60\text{ }\Omega$; $C_L = 100\text{ pF}$ unless specified otherwise. All voltages are defined with respect to ground. All values are specified per transceiver.^[1]

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--|--------------------------------------|--|--------------------|-----|-----|---------------|
| Transceiver timing; pins CANH1, CANH2, CANL1, CANL2, TXD1, TXD2, RXD1 and RXD2; see Figure 7 and Figure 4 | | | | | | |
| $t_{d(\text{TXD-busdom})}$ | delay time from TXD to bus dominant | Normal mode | - | 65 | - | ns |
| $t_{d(\text{TXD-busrec})}$ | delay time from TXD to bus recessive | Normal mode | - | 90 | - | ns |
| $t_{d(\text{busdom-RXD})}$ | delay time from bus dominant to RXD | Normal mode | - | 60 | - | ns |
| $t_{d(\text{busrec-RXD})}$ | delay time from bus recessive to RXD | Normal mode | - | 65 | - | ns |
| $t_{d(\text{TXDL-RXDL})}$ | delay time from TXD LOW to RXD LOW | Normal mode | 50 | - | 210 | ns |
| | | Normal mode; $R_L = 120\text{ }\Omega$; $C_L = 200\text{ pF}$ | ^[2] - | - | 300 | ns |
| $t_{d(\text{TXDH-RXDH})}$ | delay time from TXD HIGH to RXD HIGH | Normal mode | 50 | - | 210 | ns |
| | | Normal mode; $R_L = 120\text{ }\Omega$; $C_L = 200\text{ pF}$ | ^[2] - | - | 300 | ns |
| $t_{\text{bit}(\text{bus})}$ | transmitted recessive bit width | $t_{\text{bit}(\text{TXD})} = 500\text{ ns}$ | ^[3] 435 | - | 530 | ns |
| | | $t_{\text{bit}(\text{TXD})} = 200\text{ ns}$ | ^[3] 155 | - | 210 | ns |
| $t_{\text{bit}(\text{RXD})}$ | bit time on pin RXD | $t_{\text{bit}(\text{TXD})} = 500\text{ ns}$ | ^[3] 400 | - | 550 | ns |
| | | $t_{\text{bit}(\text{TXD})} = 200\text{ ns}$ | ^[3] 120 | - | 220 | ns |
| Δt_{rec} | receiver timing symmetry | $t_{\text{bit}(\text{TXD})} = 500\text{ ns}$ | -65 | - | +40 | ns |
| | | $t_{\text{bit}(\text{TXD})} = 200\text{ ns}$ | -45 | - | +15 | ns |
| $t_{\text{to}(\text{dom})\text{TXD}}$ | TXD dominant time-out time | $V_{\text{TXDx}} = 0\text{ V}$; Normal mode | 0.8 | 3 | 6.5 | ms |
| $t_{d(\text{stb-norm})}$ | standby to normal mode delay time | | 7 | 25 | 47 | μs |
| $t_{\text{wake}(\text{busdom})}$ | bus dominant wake-up time | Standby mode | 0.5 | - | 3 | μs |
| $t_{\text{wake}(\text{busrec})}$ | bus recessive wake-up time | Standby mode | 0.5 | - | 3 | μs |
| $t_{\text{to}(\text{wake})\text{bus}}$ | bus wake-up time-out time | Standby mode | 0.8 | 3 | 6.5 | ms |
| $t_{\text{ftr}(\text{wake})\text{bus}}$ | bus wake-up filter time | Standby mode | 0.5 | 1 | 3 | μs |

[1] All parameters are guaranteed over the virtual junction temperature range by design. Factory testing uses correlated test conditions to cover the specified temperature and power supply voltage range.

[2] Not tested in production; guaranteed by design.

[3] See [Figure 5](#).

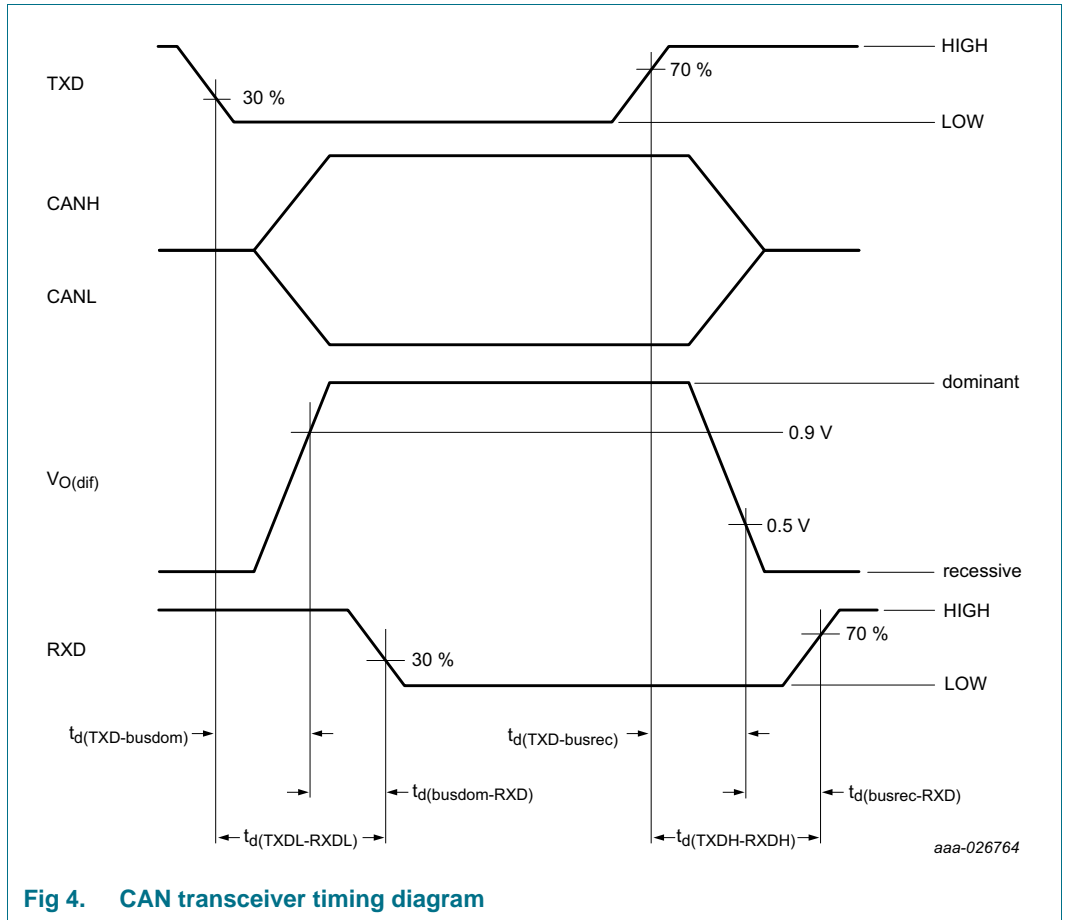


Fig 4. CAN transceiver timing diagram

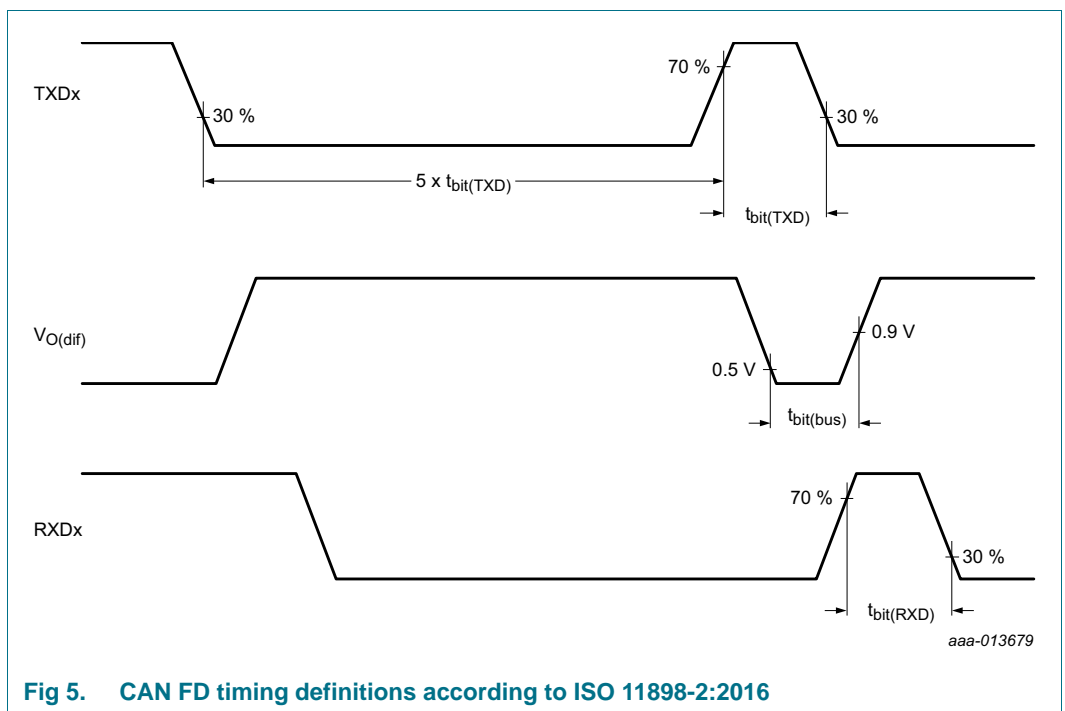
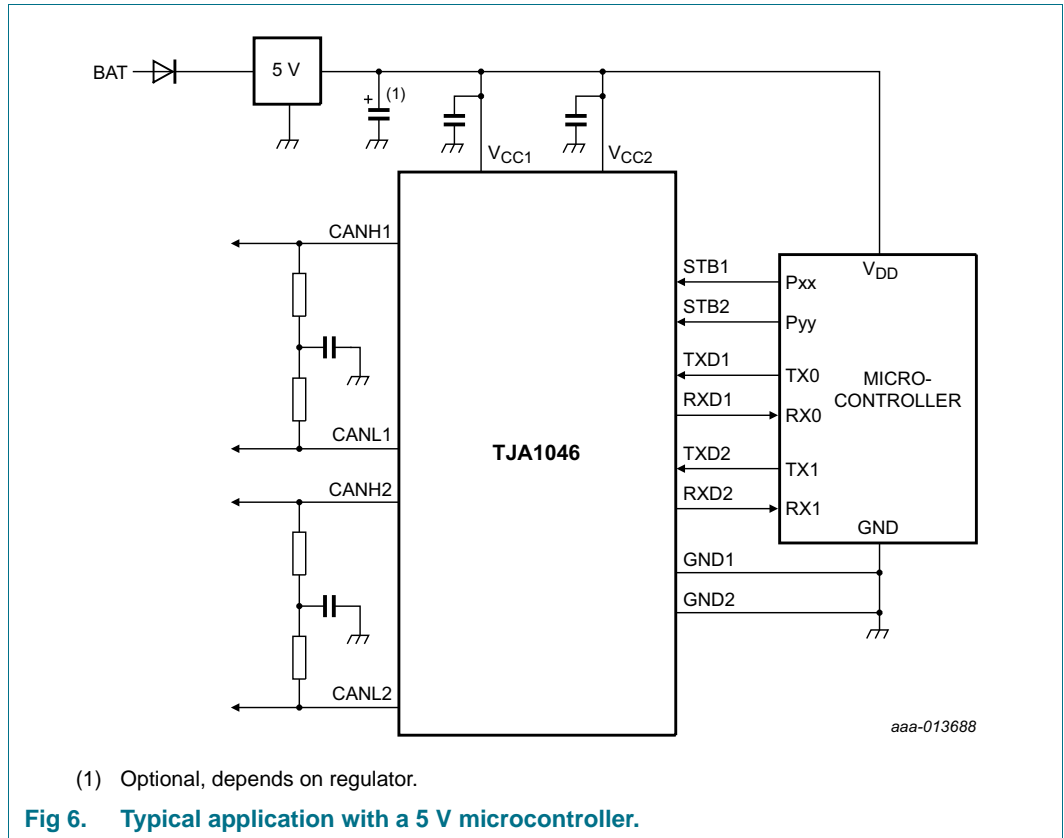


Fig 5. CAN FD timing definitions according to ISO 11898-2:2016

12. Application information

12.1 Application diagram



12.2 Application hints

Further information on the application of the TJA1046 can be found in NXP application hints AH1308 'Application Hints - Standalone high speed CAN transceivers Mantis TJA1044/TJA1057 and Dual-Mantis TJA1046'.

13. Test information

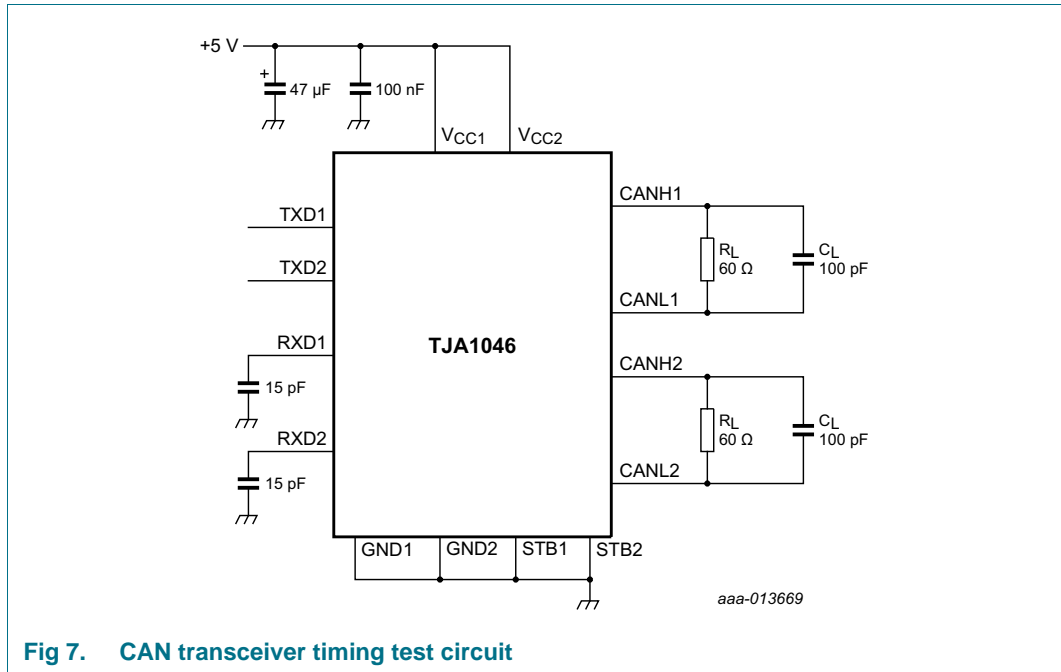


Fig 7. CAN transceiver timing test circuit

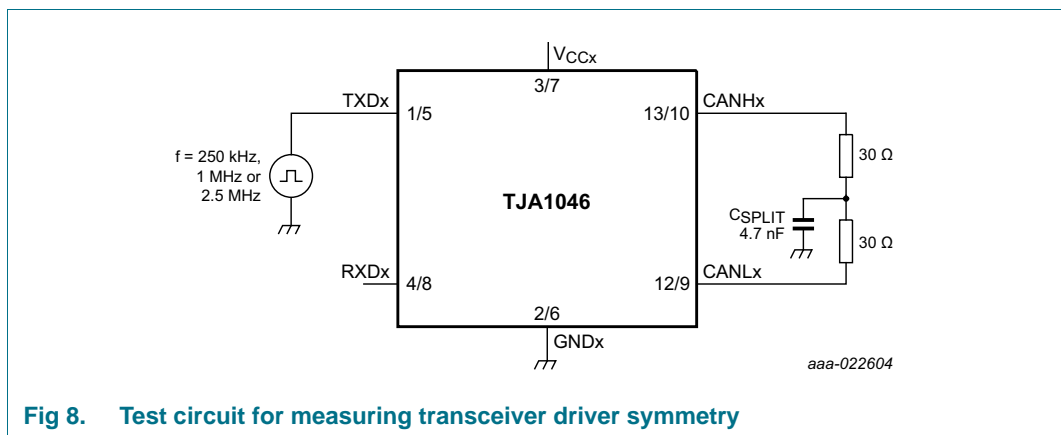


Fig 8. Test circuit for measuring transceiver driver symmetry

13.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q100 Rev-G - *Failure mechanism based stress test qualification for integrated circuits*, and is suitable for use in automotive applications.

14. Package outline

HVSON14: plastic, thermal enhanced very thin small outline package; no leads; 14 terminals; body 3 x 4.5 x 0.85 mm

SOT1086-2

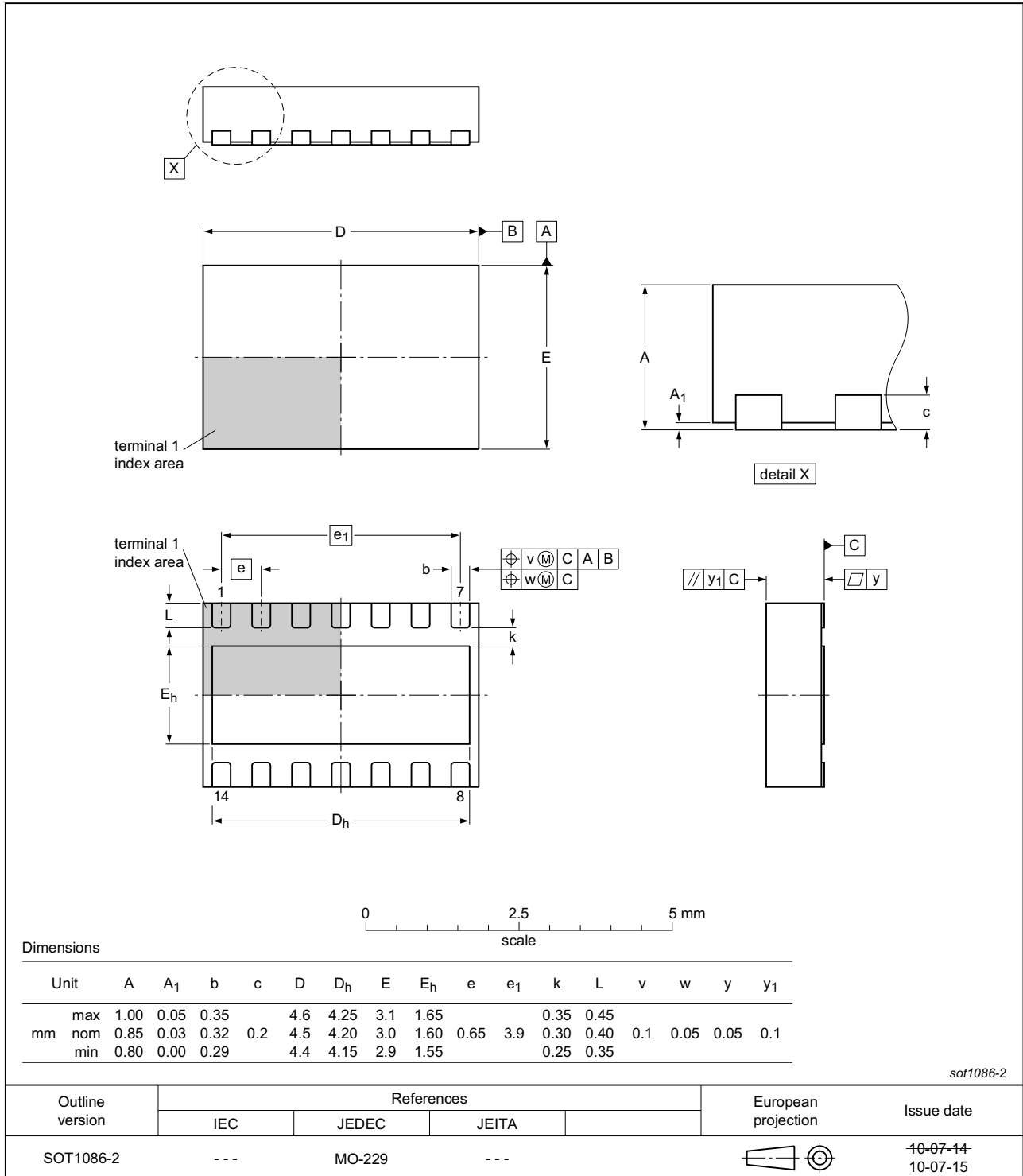


Fig 9. Package outline SOT1086-2 (HVSON14)

15. Handling information

All input and output pins are protected against ElectroStatic Discharge (ESD) under normal handling. When handling ensure that the appropriate precautions are taken as described in *JESD625-A* or equivalent standards.

16. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

16.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

16.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

16.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

16.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see [Figure 10](#)) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with [Table 9](#) and [10](#)

Table 9. SnPb eutectic process (from J-STD-020D)

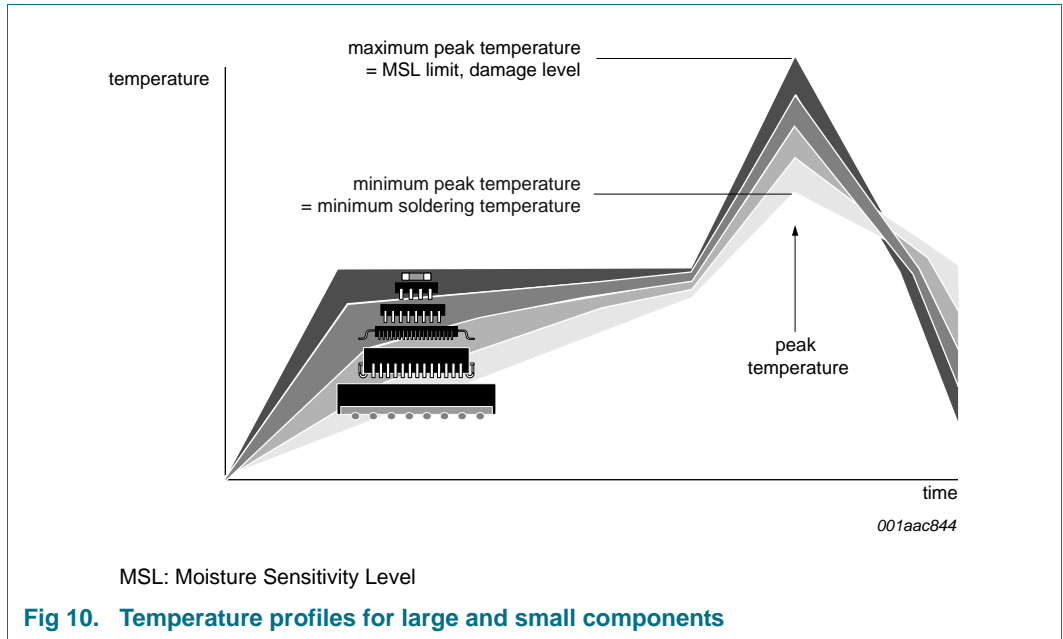
| Package thickness (mm) | Package reflow temperature (°C) | |
|------------------------|---------------------------------|-------|
| | Volume (mm ³) | |
| | < 350 | ≥ 350 |
| < 2.5 | 235 | 220 |
| ≥ 2.5 | 220 | 220 |

Table 10. Lead-free process (from J-STD-020D)

| Package thickness (mm) | Package reflow temperature (°C) | | |
|------------------------|---------------------------------|-------------|--------|
| | Volume (mm ³) | | |
| | < 350 | 350 to 2000 | > 2000 |
| < 1.6 | 260 | 260 | 260 |
| 1.6 to 2.5 | 260 | 250 | 245 |
| > 2.5 | 250 | 245 | 245 |

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see [Figure 10](#).



For further information on temperature profiles, refer to Application Note AN10365 “Surface mount reflow soldering description”.

17. Appendix: ISO 11898-2:2016 parameter cross-reference list

Table 11. ISO 11898-2:2016 to NXP data sheet parameter conversion

| ISO 11898-2:2016 | | NXP data sheet | |
|--|------------------------------|--------------------|---|
| Parameter | Notation | Symbol | Parameter |
| HS-PMA dominant output characteristics | | | |
| Single ended voltage on CAN_H | V_{CAN_H} | $V_{O(dom)}$ | dominant output voltage |
| Single ended voltage on CAN_L | V_{CAN_L} | | |
| Differential voltage on normal bus load | V_{Diff} | $V_{O(dif)}$ | differential output voltage |
| Differential voltage on effective resistance during arbitration | | | |
| Optional: Differential voltage on extended bus load range | | | |
| HS-PMA driver symmetry | | | |
| Driver symmetry | V_{SYM} | V_{TXsym} | transmitter voltage symmetry |
| Maximum HS-PMA driver output current | | | |
| Absolute current on CAN_H | I_{CAN_H} | $I_{O(sc)dom}$ | dominant short-circuit output current |
| Absolute current on CAN_L | I_{CAN_L} | | |
| HS-PMA recessive output characteristics, bus biasing active/inactive | | | |
| Single ended output voltage on CAN_H | V_{CAN_H} | $V_{O(rec)}$ | recessive output voltage |
| Single ended output voltage on CAN_L | V_{CAN_L} | | |
| Differential output voltage | V_{Diff} | $V_{O(dif)}$ | differential output voltage |
| Optional HS-PMA transmit dominant timeout | | | |
| Transmit dominant timeout, long | t_{dom} | $t_{to(dom)TXD}$ | TXD dominant time-out time |
| Transmit dominant timeout, short | | | |
| HS-PMA static receiver input characteristics, bus biasing active/inactive | | | |
| Recessive state differential input voltage range | V_{Diff} | $V_{th(RX)dif}$ | differential receiver threshold voltage |
| Dominant state differential input voltage range | | $V_{rec(RX)}$ | receiver recessive voltage |
| | | $V_{dom(RX)}$ | receiver dominant voltage |
| HS-PMA receiver input resistance (matching) | | | |
| Differential internal resistance | R_{Diff} | $R_{i(dif)}$ | differential input resistance |
| Single ended internal resistance | R_{CAN_H} R_{CAN_L} | R_i | input resistance |
| Matching of internal resistance | MR | ΔR_i | input resistance deviation |
| HS-PMA implementation loop delay requirement | | | |
| Loop delay | t_{Loop} | $t_{d(TXDH-RXDH)}$ | delay time from TXD HIGH to RXD HIGH |
| | | $t_{d(TXDL-RXDL)}$ | delay time from TXD LOW to RXD LOW |
| Optional HS-PMA implementation data signal timing requirements for use with bit rates above 1 Mbit/s up to 2 Mbit/s and above 2 Mbit/s up to 5 Mbit/s | | | |
| Transmitted recessive bit width @ 2 Mbit/s / @ 5 Mbit/s, intended | $t_{Bit(Bus)}$ | $t_{bit(bus)}$ | transmitted recessive bit width |
| Received recessive bit width @ 2 Mbit/s / @ 5 Mbit/s | $t_{Bit(RXD)}$ | $t_{bit(RXD)}$ | bit time on pin RXD |
| Receiver timing symmetry @ 2 Mbit/s / @ 5 Mbit/s | Δt_{Rec} | Δt_{rec} | receiver timing symmetry |

Table 11. ISO 11898-2:2016 to NXP data sheet parameter conversion

| ISO 11898-2:2016 | | NXP data sheet | |
|---|------------------------------|-----------------------------------|---------------------------------------|
| Parameter | Notation | Symbol | Parameter |
| HS-PMA maximum ratings of V_{CAN_H}, V_{CAN_L} and V_{Diff} | | | |
| Maximum rating V_{Diff} | V_{Diff} | $V_{(CANH-CANL)}$ | voltage between pin CANH and pin CANL |
| General maximum rating V_{CAN_H} and V_{CAN_L} | V_{CAN_H} | V_x | voltage on pin x |
| Optional: Extended maximum rating V_{CAN_H} and V_{CAN_L} | V_{CAN_L} | | |
| HS-PMA maximum leakage currents on CAN_H and CAN_L, unpowered | | | |
| Leakage current on CAN_H, CAN_L | I_{CAN_H} I_{CAN_L} | I_L | leakage current |
| HS-PMA bus biasing control timings | | | |
| CAN activity filter time, long | t_{Filter} | $t_{wake(busdom)}$ ^[1] | bus dominant wake-up time |
| CAN activity filter time, short | | $t_{wake(busrec)}$ ^[1] | bus recessive wake-up time |
| Wake-up timeout, short | t_{Wake} | $t_{to(wake)bus}$ | bus wake-up time-out time |
| Wake-up timeout, long | | | |
| Timeout for bus inactivity | $t_{Silence}$ | $t_{to(silence)}$ | bus silence time-out time |
| Bus Bias reaction time | t_{Bias} | $t_{d(busact-bias)}$ | delay time from bus active to bias |

[1] $t_{filtr(wake)bus}$ - bus wake-up filter time, in devices with basic wake-up functionality

18. Revision history

Table 12. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|----------------|---|--------------------|---------------|----------------|
| TJA1046 v.3 | 20170906 | Product data sheet | - | TJA1046 v.2.01 |
| Modifications: | <ul style="list-style-type: none"> • Updated to comply with ISO 11898-2:2016 and SAE J22884-1 through SAE J2284-5 specifications: <ul style="list-style-type: none"> – Section 1: text amended (last paragraph) – Section 2.1: text amended (2nd entry) – Section 7.2: text amended (1st paragraph) – Table 7: conditions added to parameters R_i, ΔR_i and $R_{i(dif)}$; values/conditions changed for parameters I_{CC}, $V_{rec(RX)}$, $V_{dom(RX)}$, $I_{O(sc)dom}$ – Table 7: Additional measurements taken at $f_{TXD} = 1$ MHz and 2.5 MHz for parameter V_{TXsym}; see Figure 8 – Figure 5: title changed • Table 5, Table note 2 added • Amended Figure 4, Figure 6, Figure 7 and Figure 8 • Section 12.2: reference updated | | | |
| TJA1046 v.2.01 | 20160523 | Product data sheet | - | TJA1046 v.1 |
| TJA1046 v.1 | 20150528 | Product data sheet | - | - |

19. Legal information

19.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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| Product [short] data sheet | Production | This document contains the product specification. |

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[2] The term 'short data sheet' is explained in section "Definitions".

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